

REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	TSP

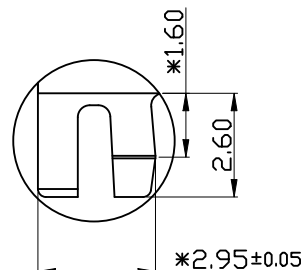
MATERIAL:

HOUSING:PA46,BLACK.
TERMINAL: PHOSPHOR BRONZE Ø0.46MM
GOLD PLATING

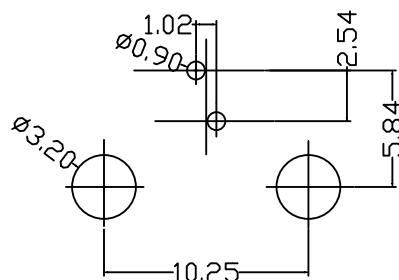
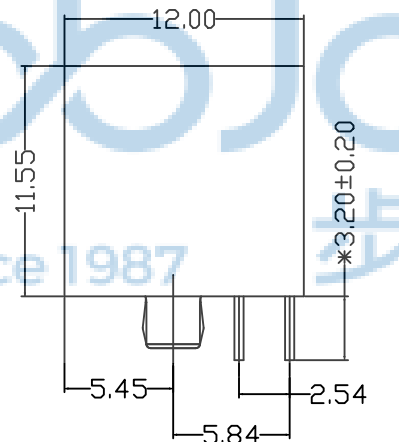
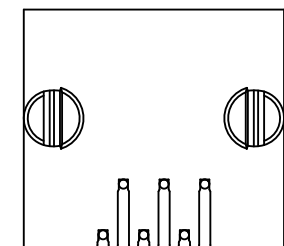
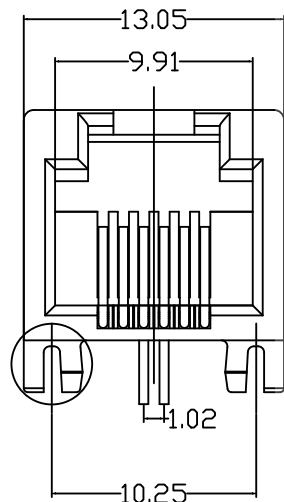
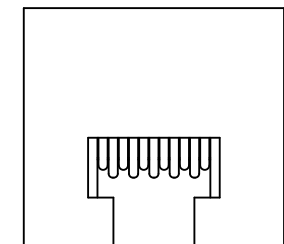
DURABILITY: 750 CYCLES MIN,12.5MM/MINUTE.
INSERTION FORCE: 2.2KG.F MAX.
RETENTION STRENGTH : 7.7KG.F BETWEEN JACK AND PLUG.
OPERATING TEMPERATURE: -40 °C~+85°C.
STORAGE TEMPERATURE: -40°C~+85°C.
ALL CRITICAL DIMENSIONS WITH "*"

VOLTAGE: 125 VOLTS AC.
CURRENT RATING : 1.5AMP.
DIELECTRIC STRENGTH: 1000 VAC RMS 50HZ OR 60HZ,1MIN.
INSULATION RESISTANCE: 500 MEGA OHMS MIN. INITIAL
AFTER 500V DC FOR 1 MINUTE.

CONTACT RESISTANCE: SINGLE TERMINAL 30 MILLIOHMS MAX.
INITIAL 50 MILLIOHMS MAX. AFTER
DURABILITY TEST.



DETAIL A
SCALE 2:1



PCB LAYOUT
THICKNESS=1.6mm

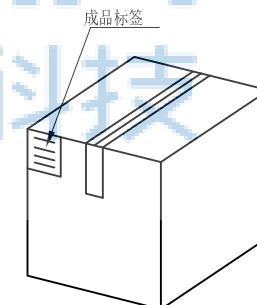
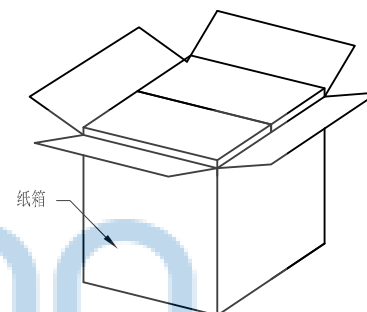
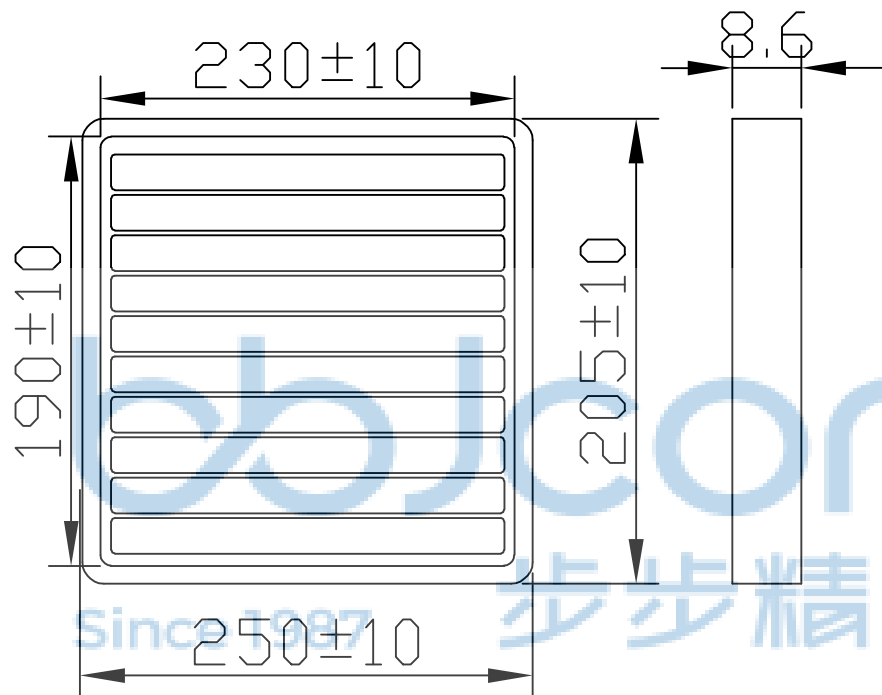
1	○	J1
2	○	J2
3	○	J3
4	○	J4
5	○	J5
6	○	J6
7	○	J7
8	○	J8

PCB SIDE TO PHY

CABLE SIDE



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.X: ±0.38 .XX: ±0.25 .XXX: ±0.13		X*: ±3* .X*: ±2* .XX*: ±1*		APPD. JM_Zheng CHKD. LYX DR. TSP	
PDWG.NO: 0067-1		PJ. NO.: 131-2K2-060003-T8G SIZE: A4 DRW NO.: FINISH: SEE NOTES MAT'L.: SEE NOTES SCALE: N/A REV.: A0 UNIT: mm PAGE: 1/2			



纸箱规格: 350*210*290



1. 包装要求:
- 1.1 每盒吸塑盒包装120pcs;
- 1.2 每20盘放一箱, 共计2400PCS;
- 1.3 纸箱外贴上标签。

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APPD.	JM_Zheng	PJ. NO.: 131-2K2-060003-T8G	
CHKD.	LYX	SIZE: A4 DRW NO.:	
DR.	TSP	FINISH: SEE NOTES	MAT'L.: SEE NOTES
		SCALE: N/A	REV.: A0 UNIT: mm PAGE: 2/2